United States Patent [19]

Koyama et al.

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[45] **Date of Patent: **Jun. 23, 1998**

[54] SEMICONDUCTOR PACKAGE

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[73] Assignee: **Sony Corporation**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **68,117**

[22] Filed: **Mar. 13, 1997**

[51] **LOC (6) Cl.** **13-03**

[52] **U.S. Cl.** **D13/182**

[58] **Field of Search** D13/182; 174/52.2–52.4; 206/710, 719; 257/254, 659, 666, 678–697, 730, 738, 780; 437/183, 217, 220

[56] **References Cited**

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Primary Examiner—James Gandy
Assistant Examiner—Cathron B. Matta
Attorney, Agent, or Firm—Foley & Lardner

[57] CLAIM

The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a first embodiment of a semiconductor package showing our new design;

FIG. **2** is a left side elevational view thereof, top plan, bottom plan and right side elevational views are the same image;

FIG. **3** is a front elevational view thereof;

FIG. **4** is a rear elevational view thereof;

FIG. **5** is a perspective view of a second embodiment of a semiconductor package showing our new design;

FIG. **6** is a top plan view of the embodiment of FIG. **5;**

FIG. **7** is a left side elevational view of the embodiment of FIG. **5;**

FIG. **8** is a front elevational view of the embodiment of FIG. **5;**

FIG. **9** is a bottom plan view of the embodiment of FIG. **5;**

FIG. **10** is a right side elevational view of the embodiment of FIG. **5;**

FIG. **11** is a rear elevational view of the embodiment of FIG. **5;**

FIG. **12** is a perspective view of a third embodiment of a semiconductor package showing our new design;

FIG. **13** is a top plan view of the embodiment of FIG. **12;**

FIG. **14** is a left side elevational view of the embodiment of FIG. **12;**

FIG. **15** is a front elevational view of the embodiment of FIG. **12;**

FIG. **16** is a bottom plan view of the embodiment of FIG. **12;**

FIG. **17** is a right side elevational view of the embodiment of FIG. **12;** and,

FIG. **18** is a rear elevational view of the embodiment of FIG. **12.**

1 Claim, 8 Drawing Sheets

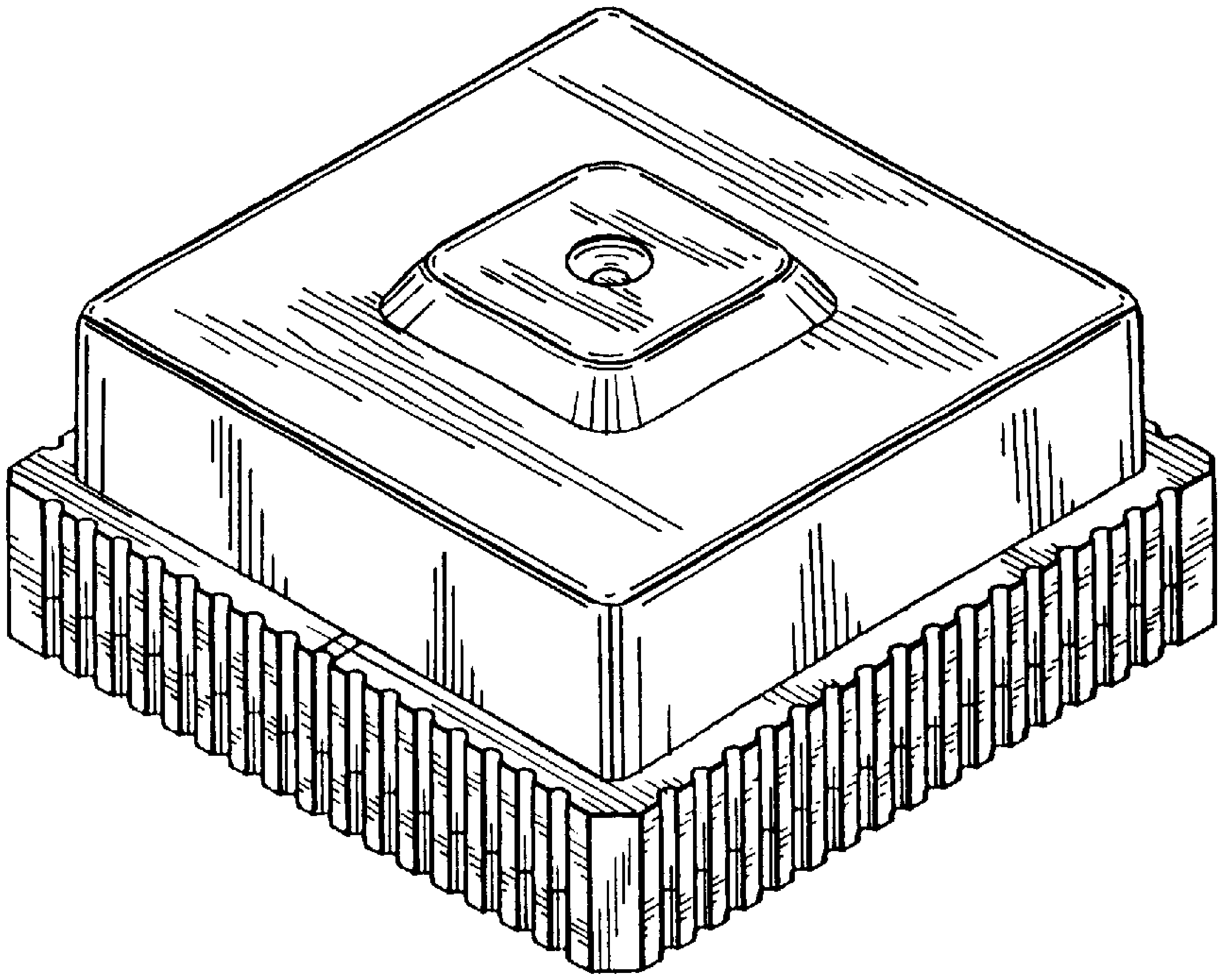

FIG. 1

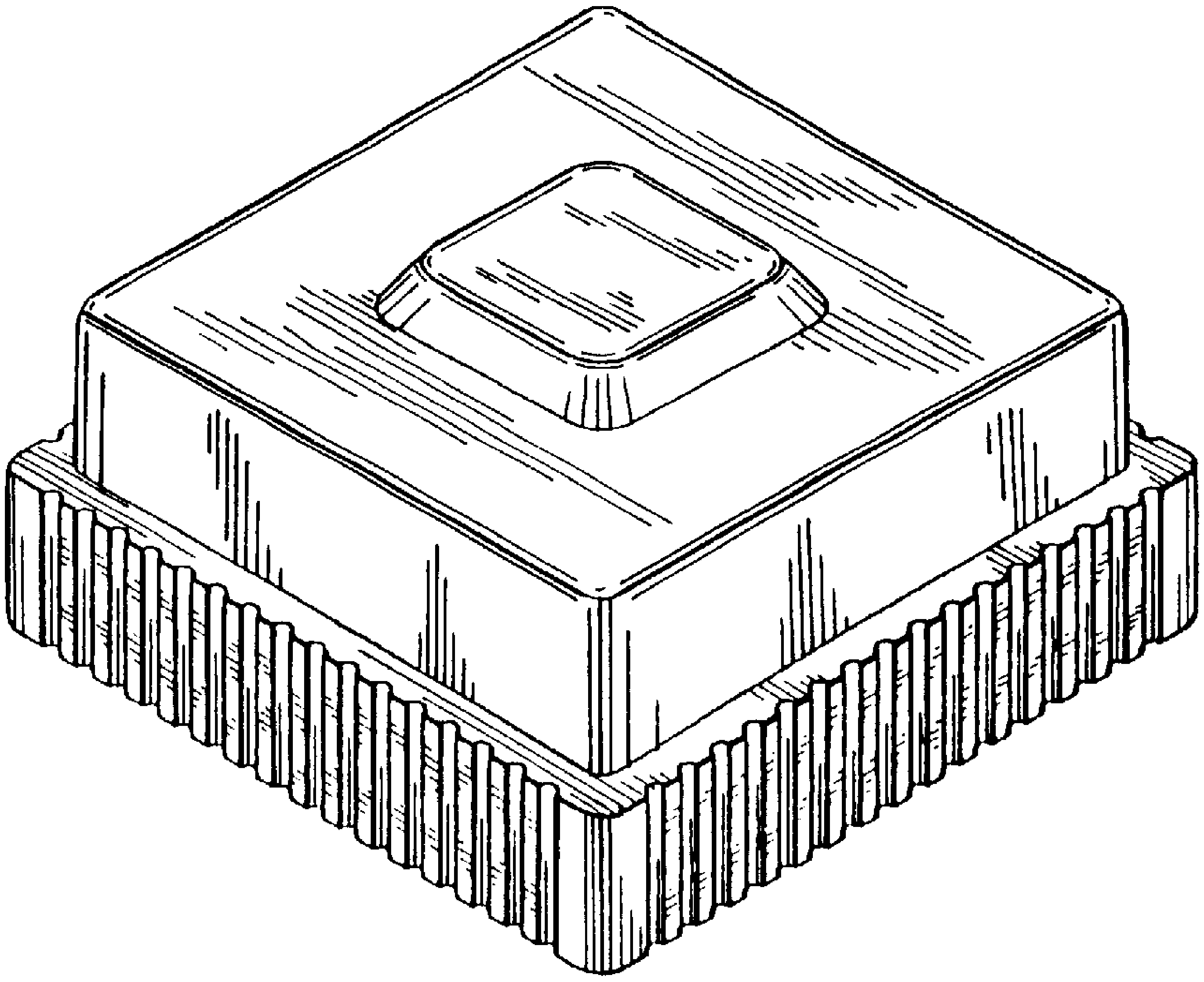

FIG. 2

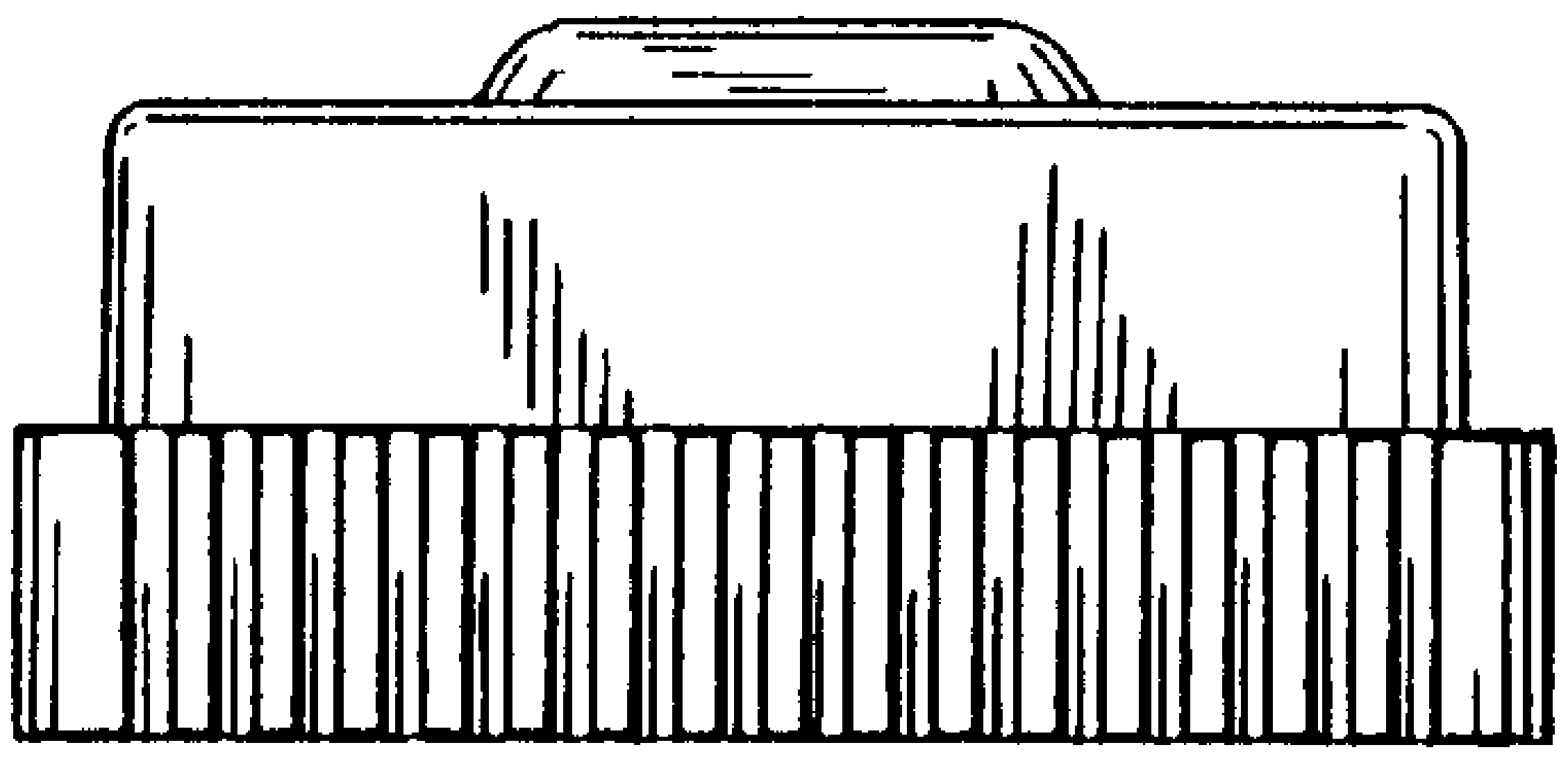

FIG. 3

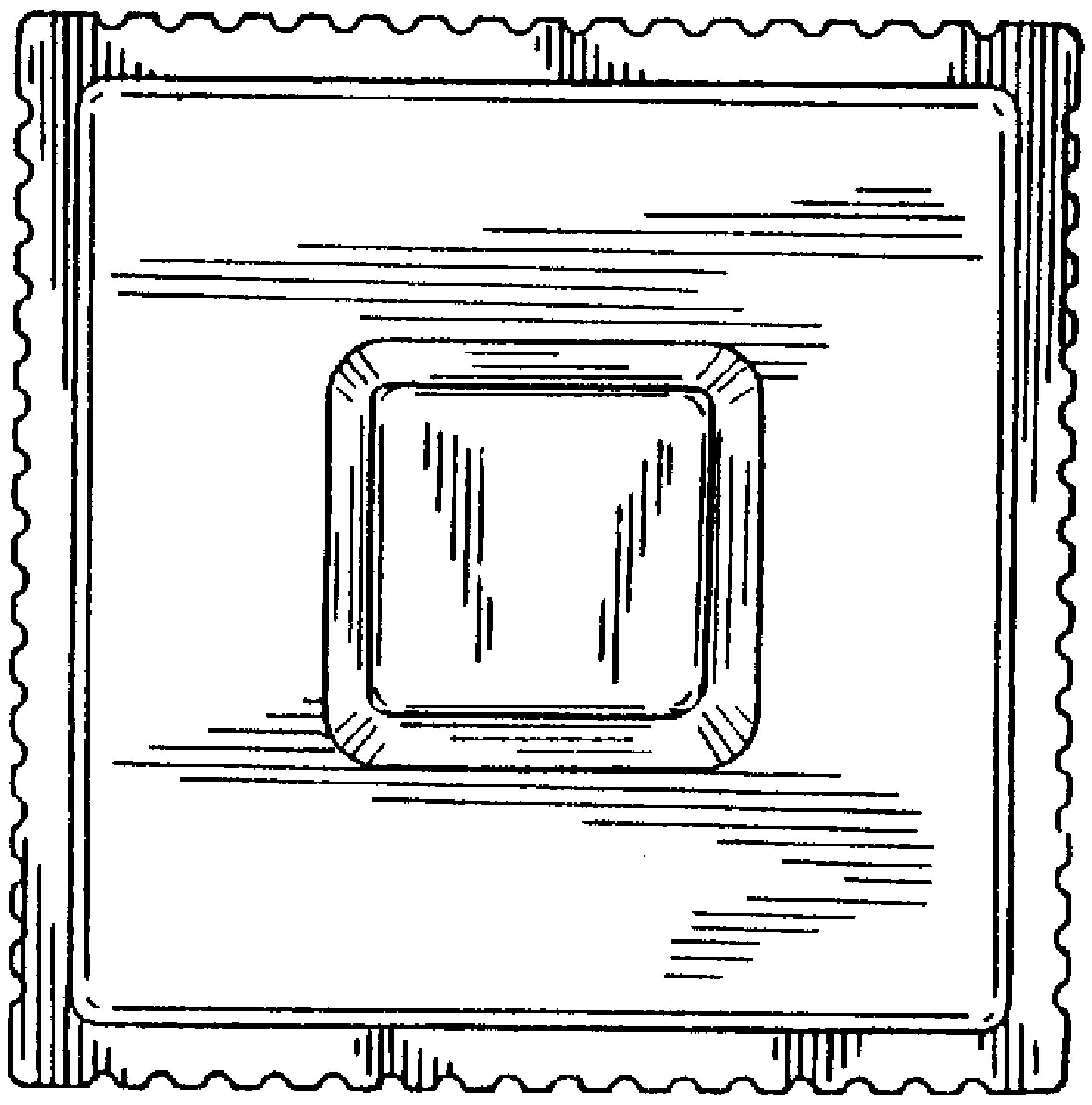

FIG. 4

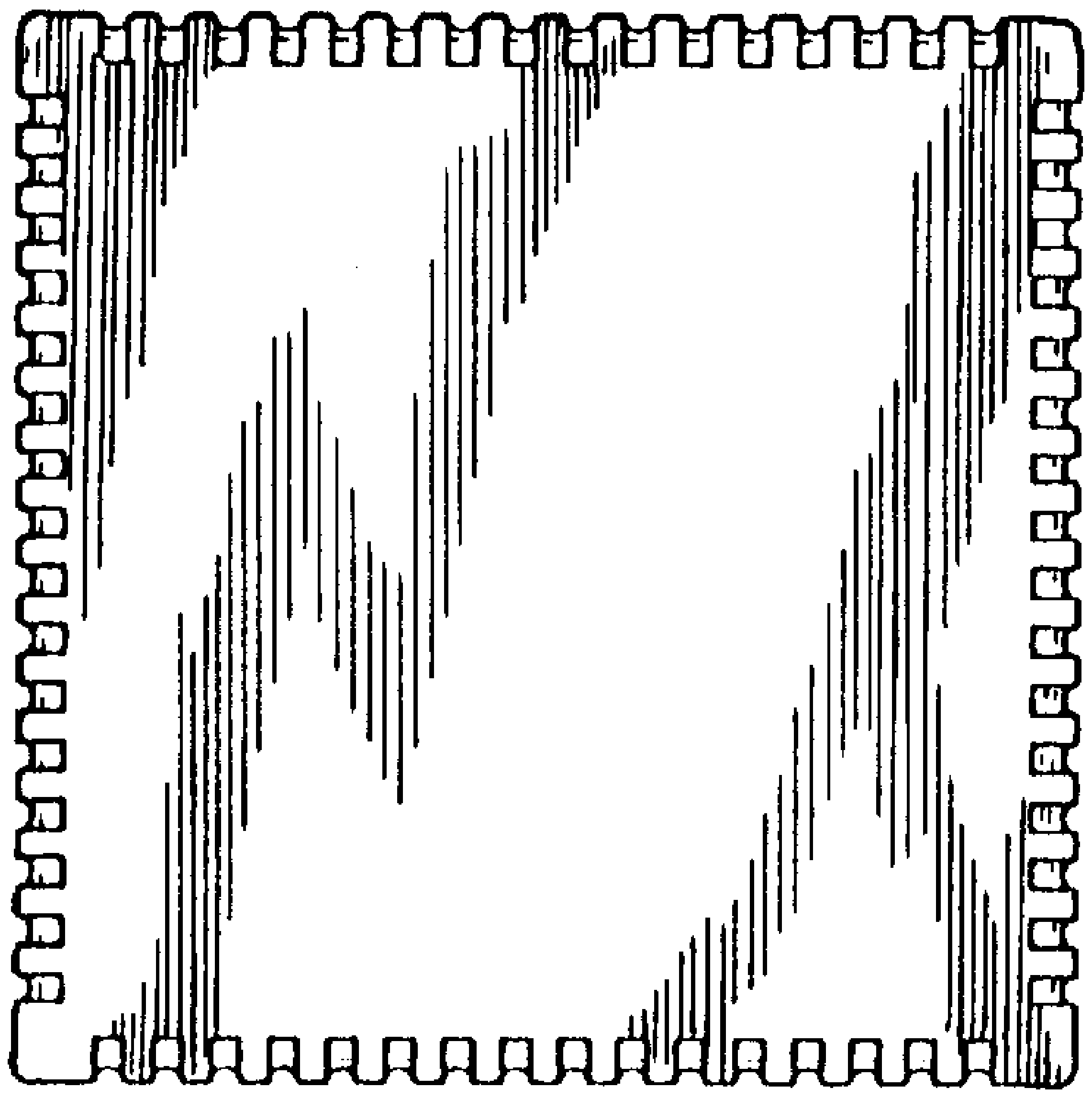

FIG. 5

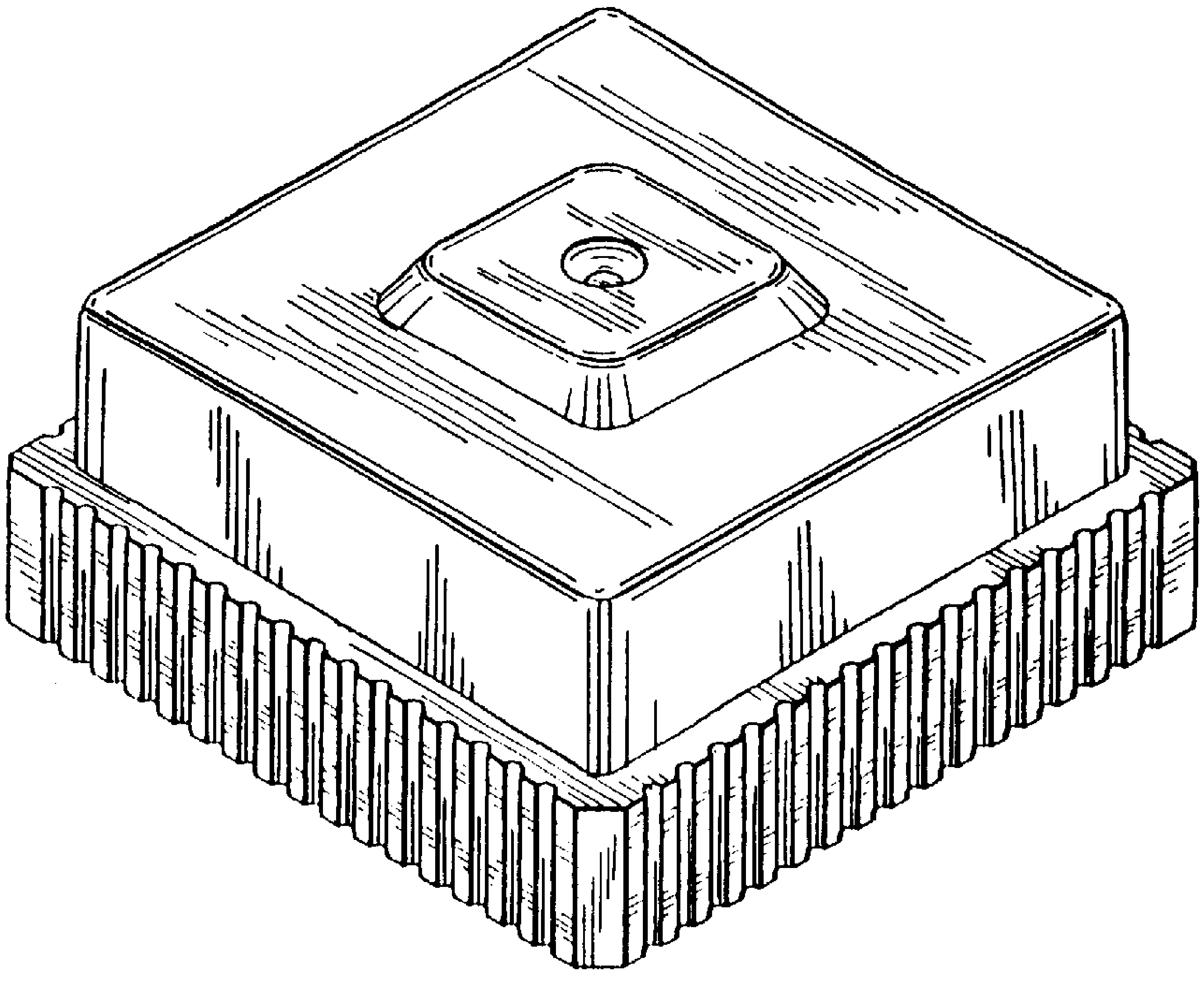

FIG. 6

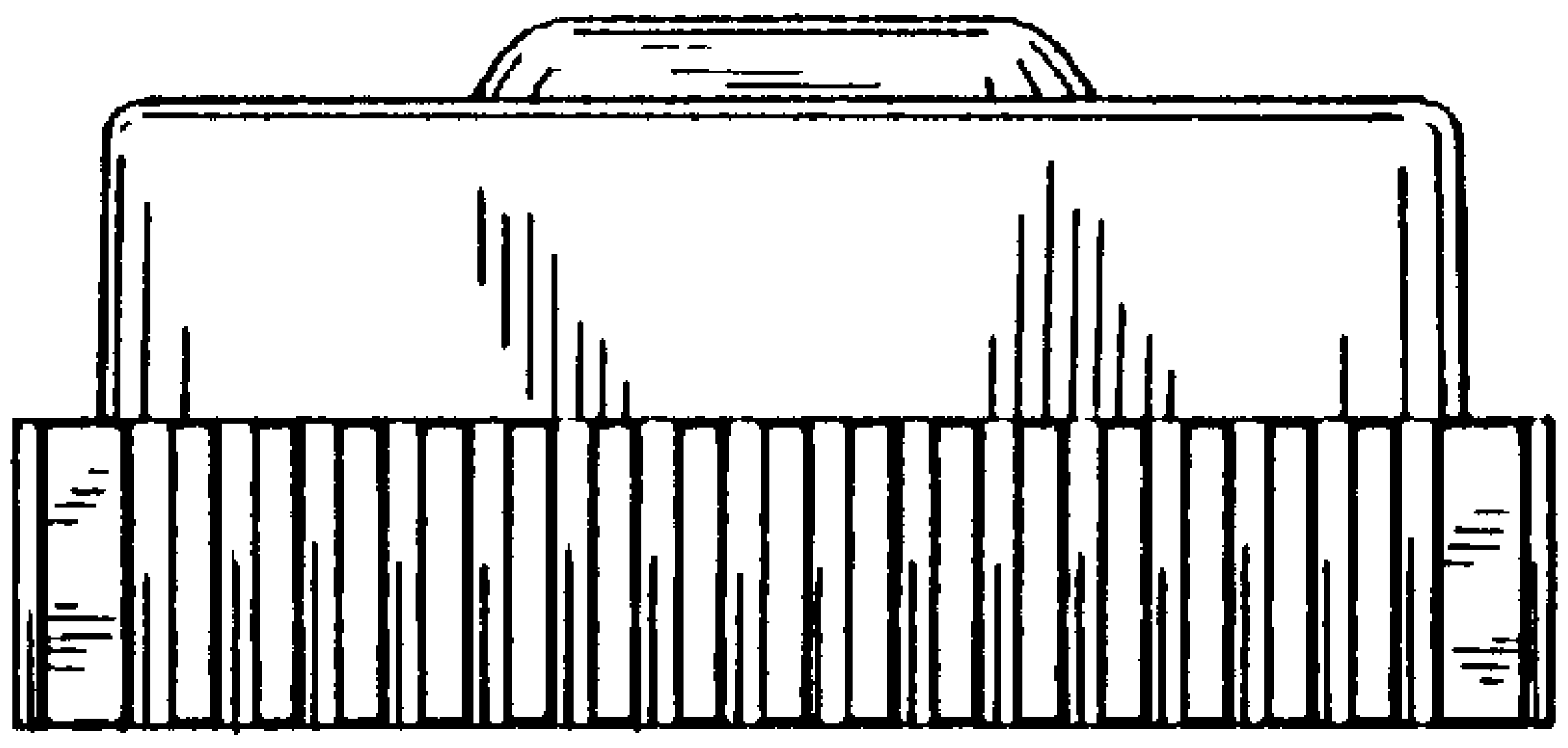

FIG. 8

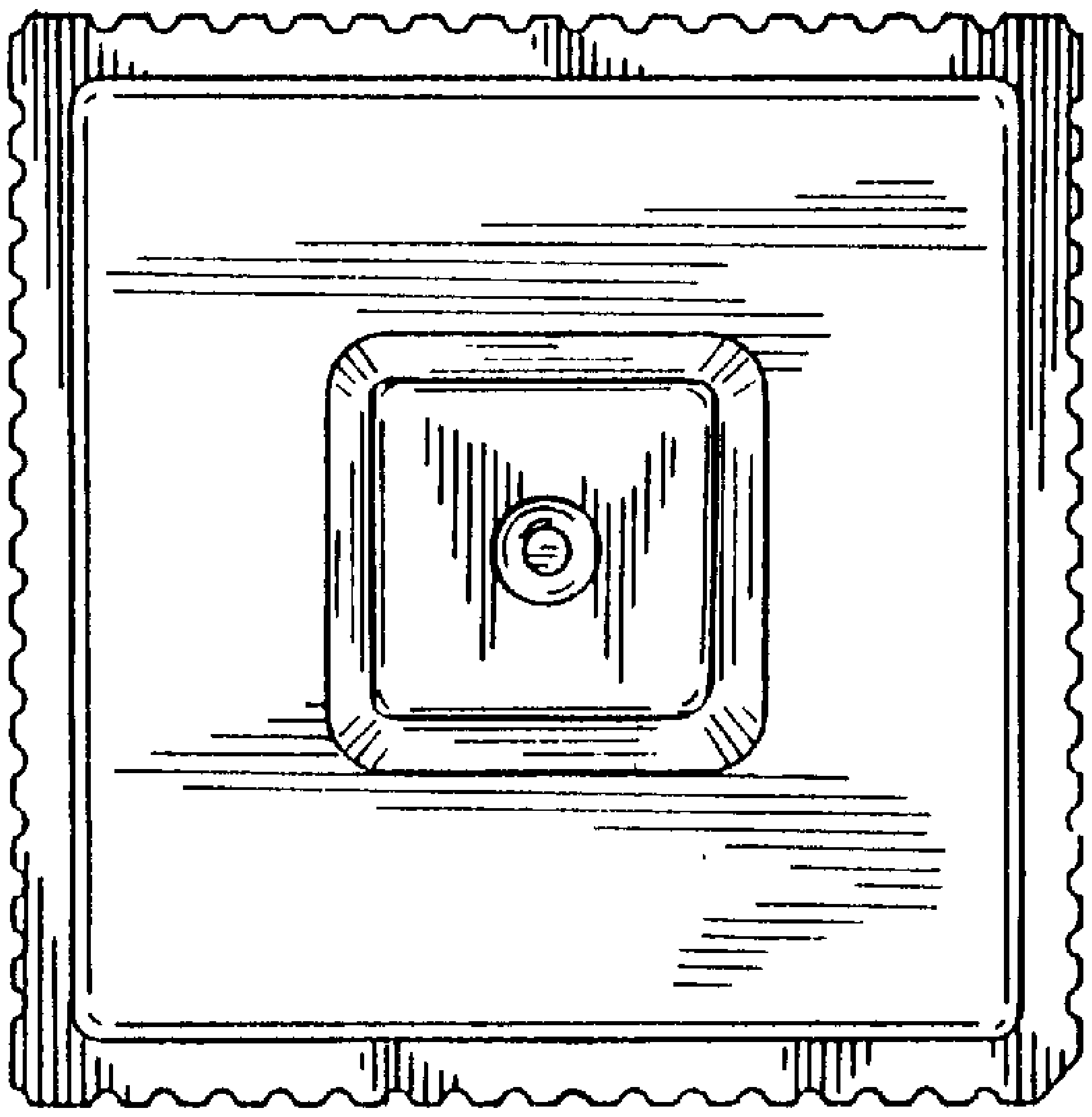

FIG. 9

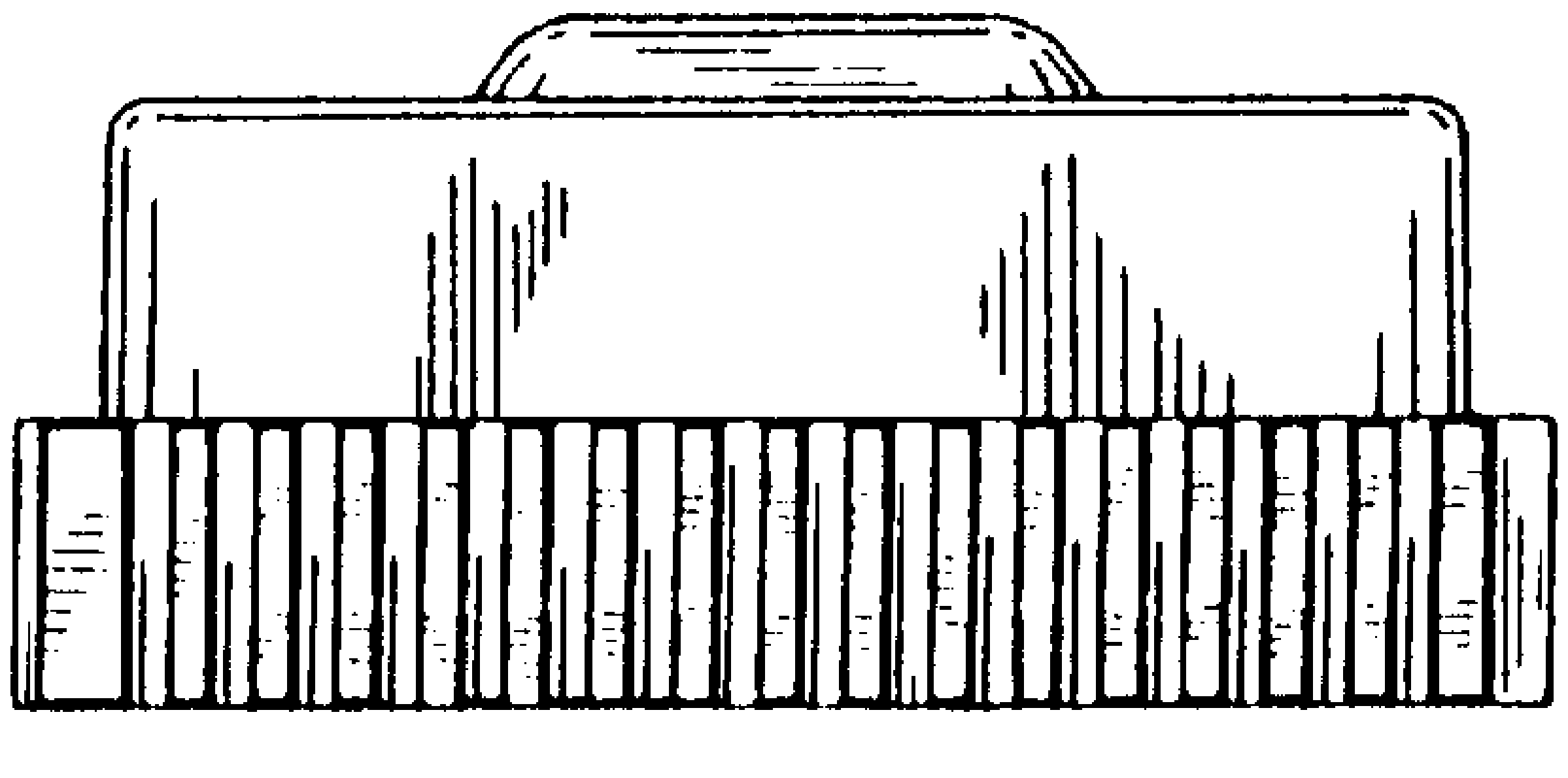

FIG. 7

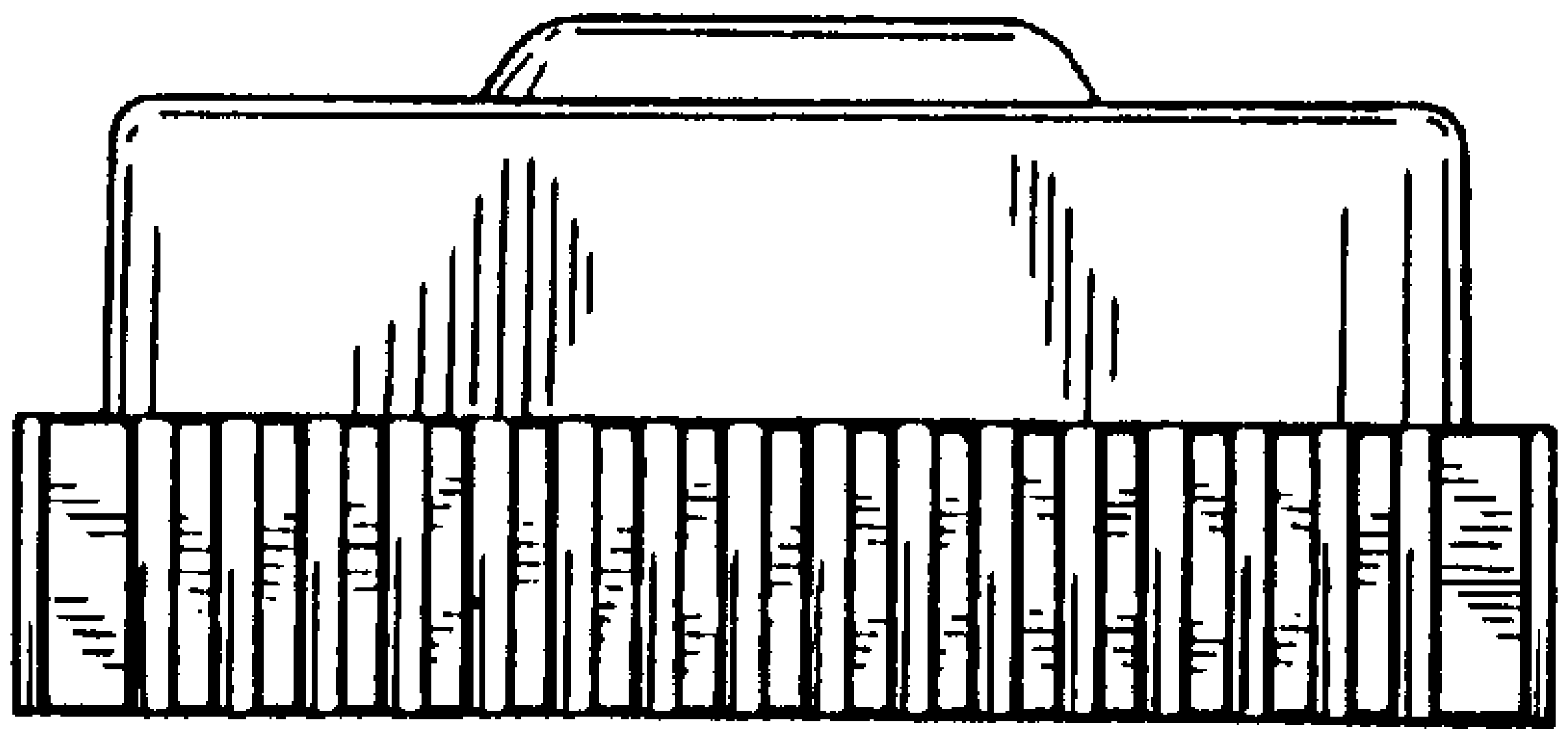

FIG. 11

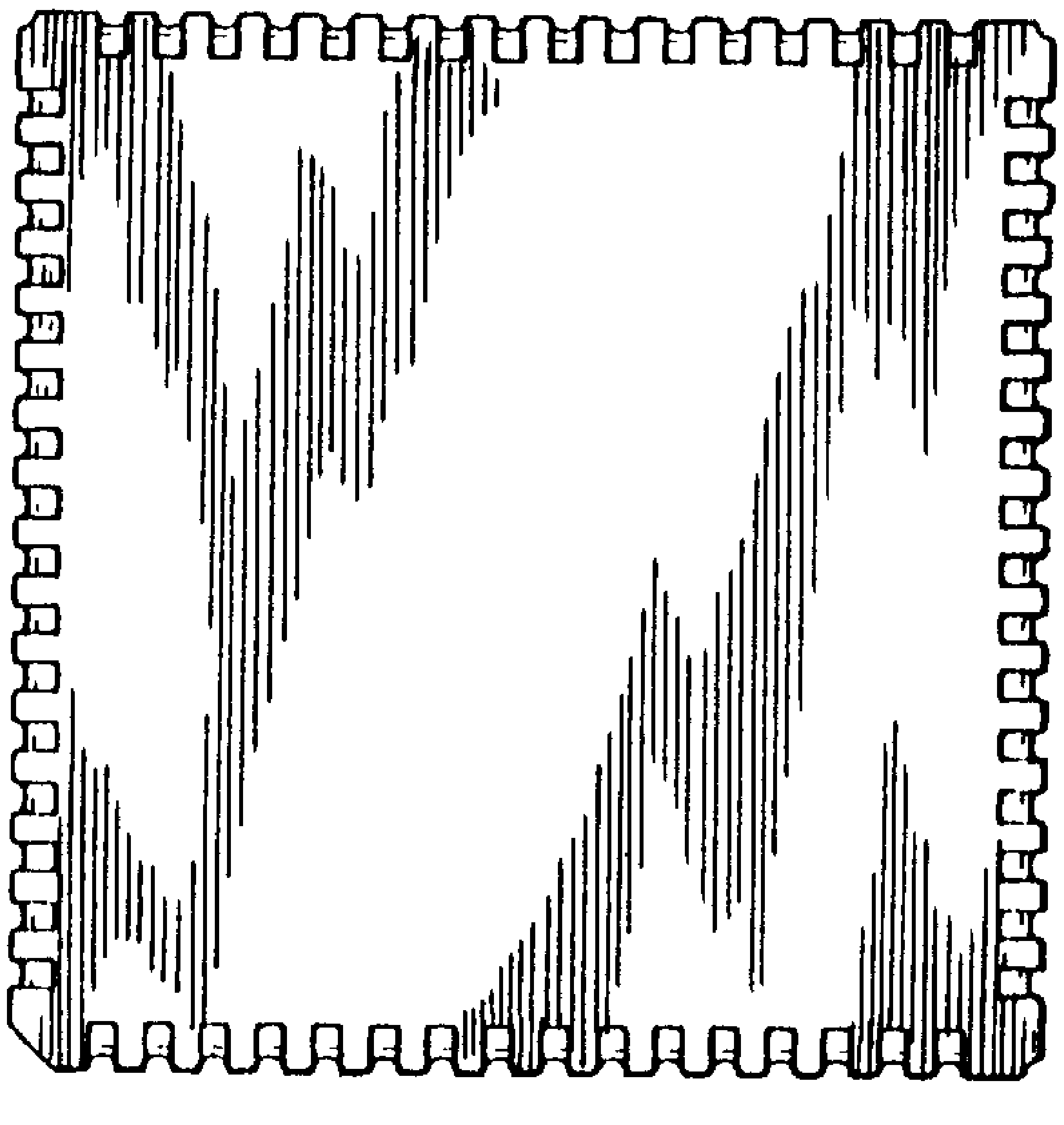

FIG. 10

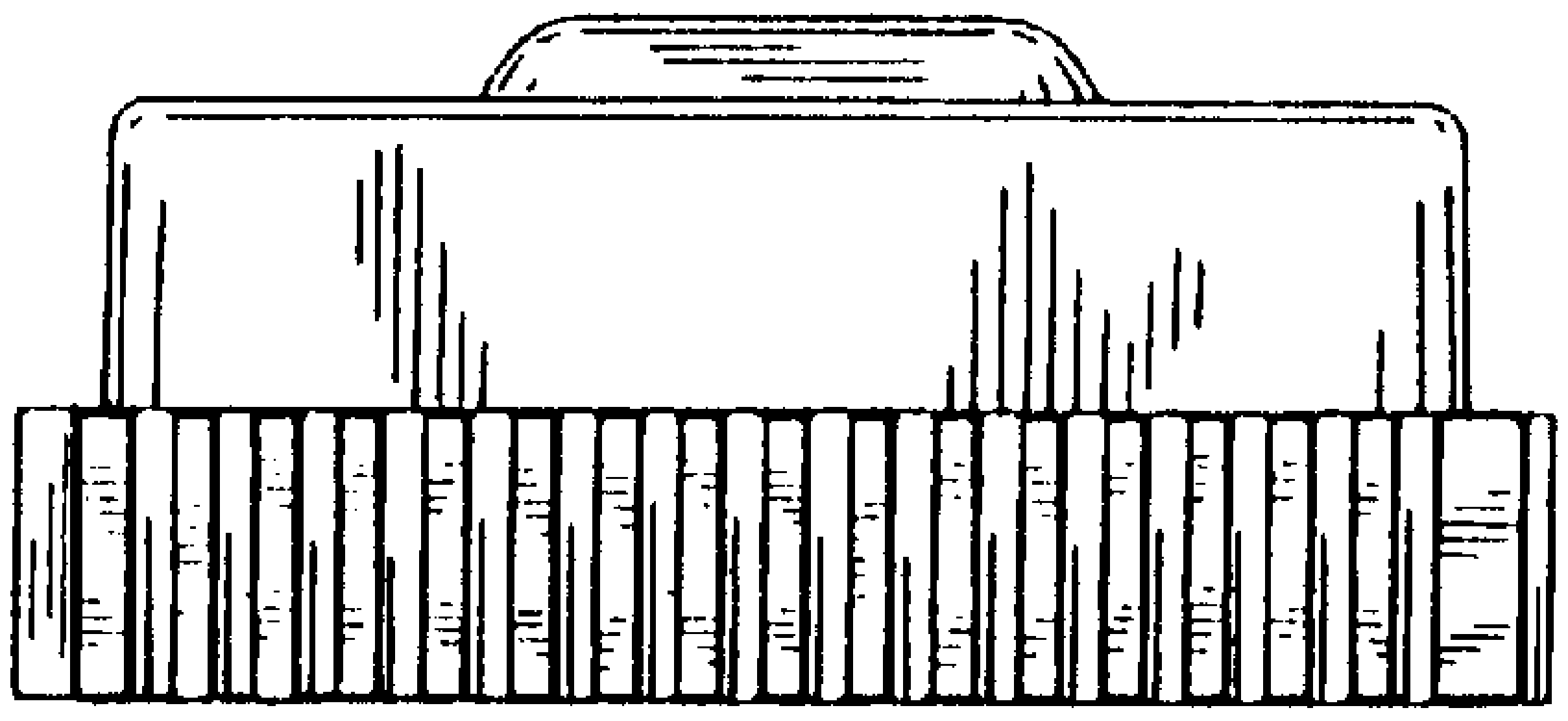

FIG. 12

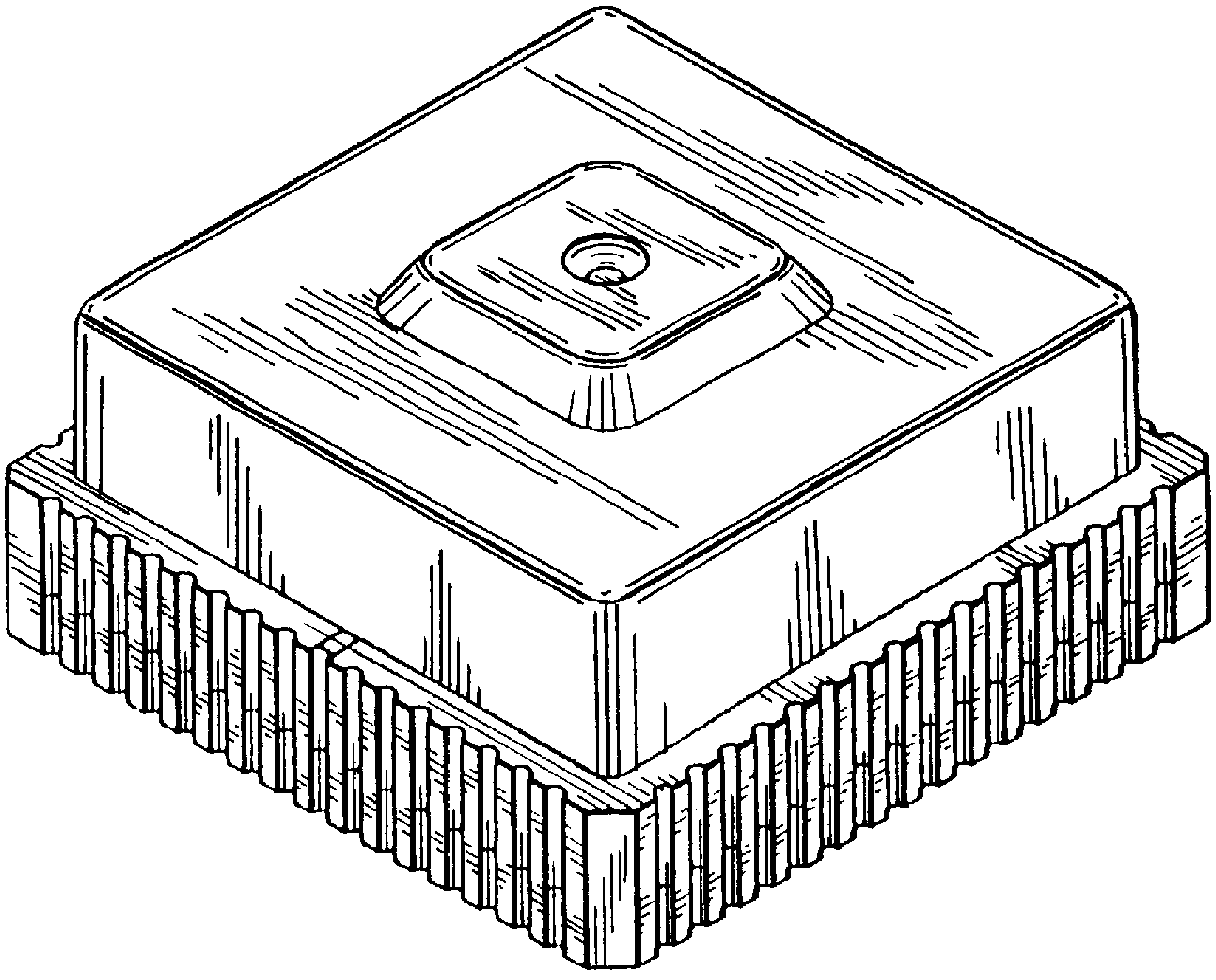

FIG. 13

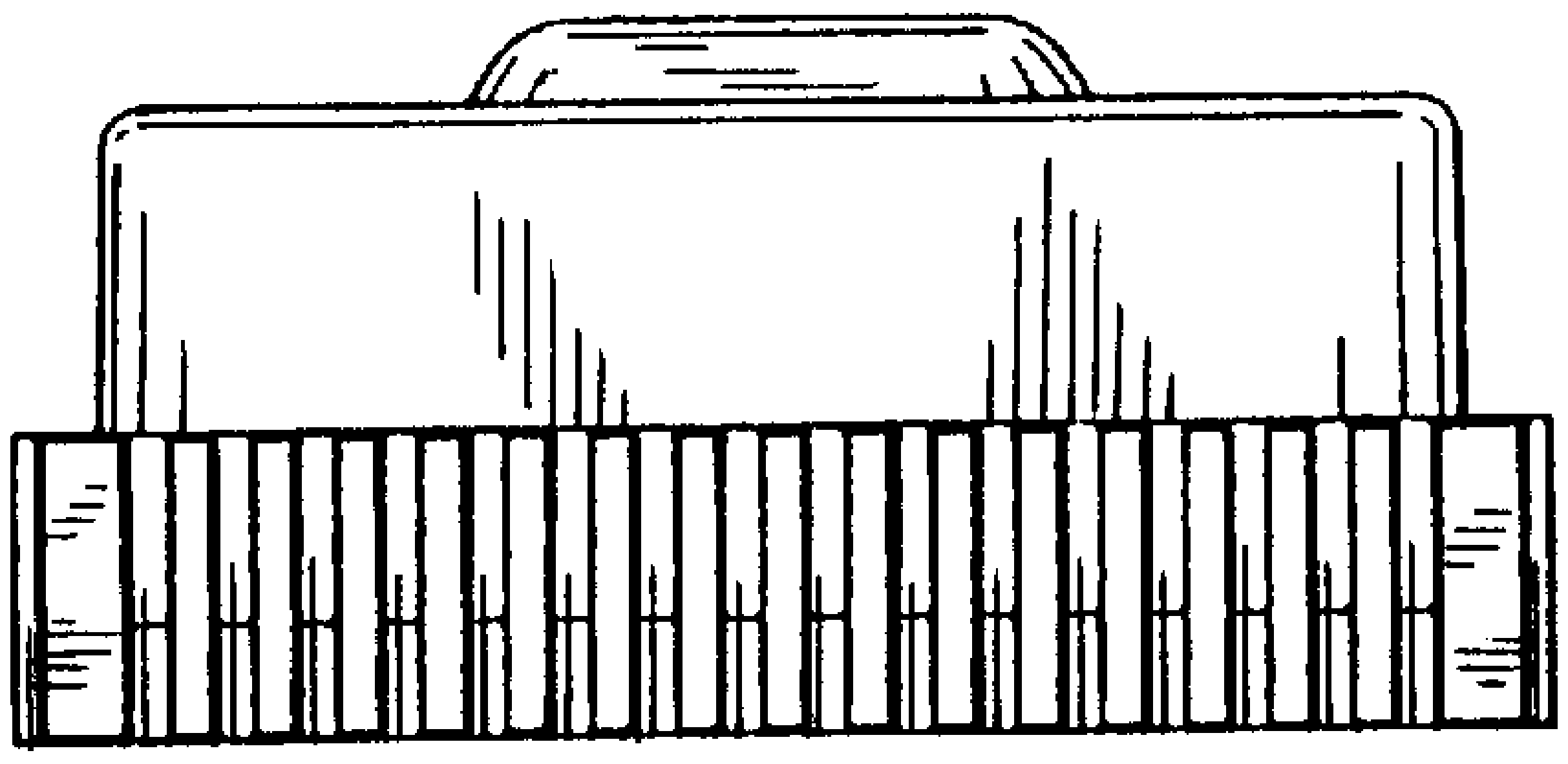

FIG. 15

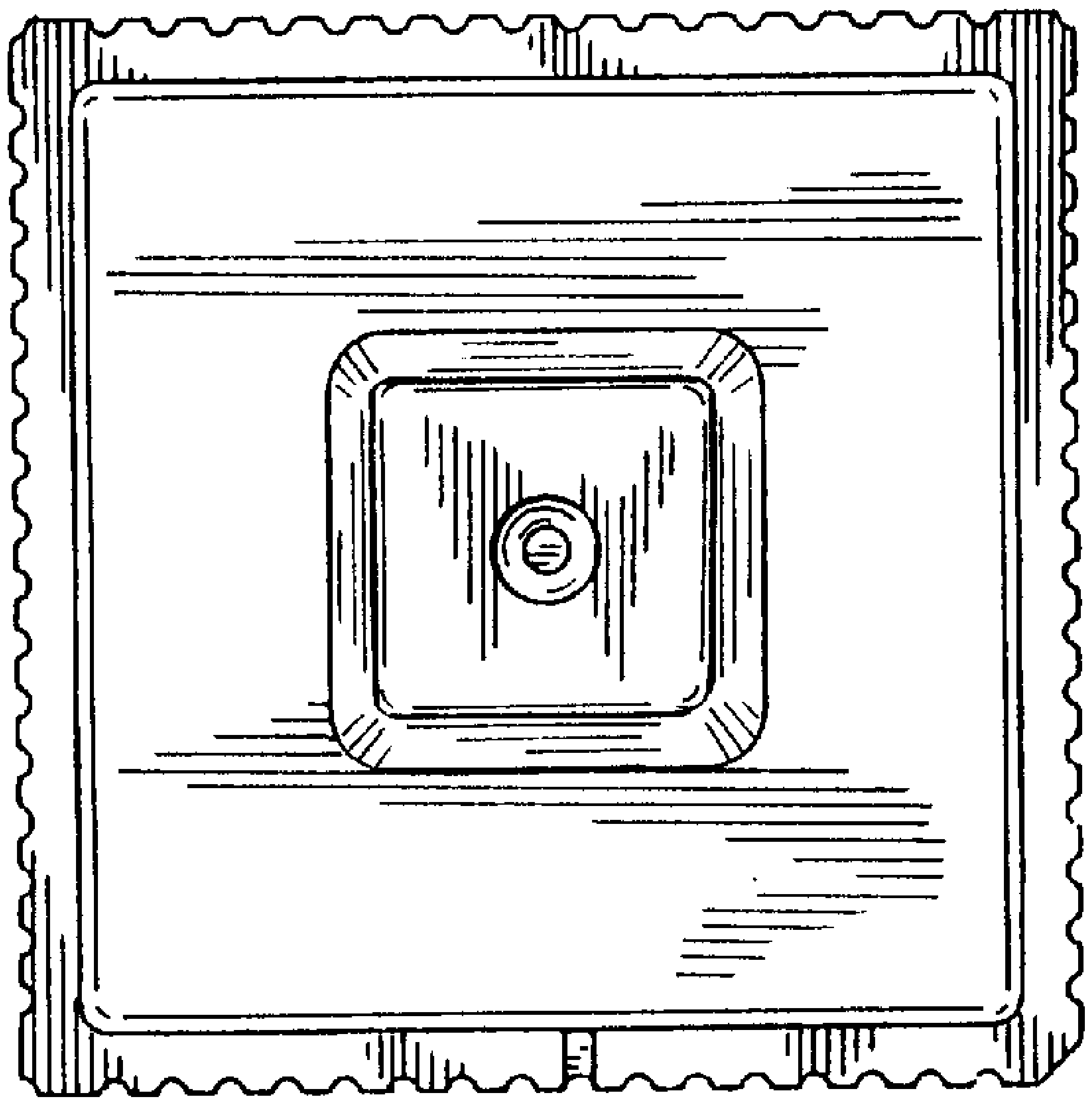

FIG. 16

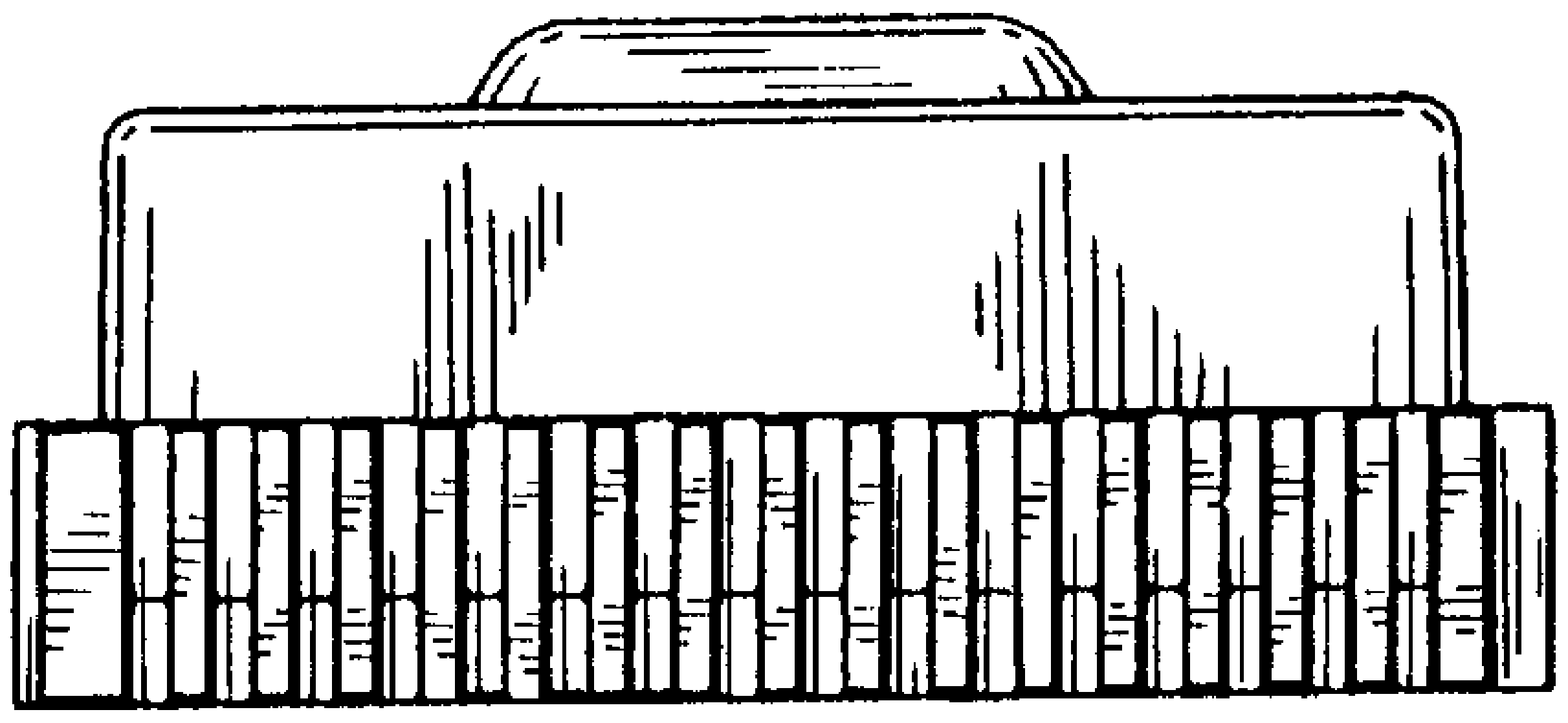

FIG. 14

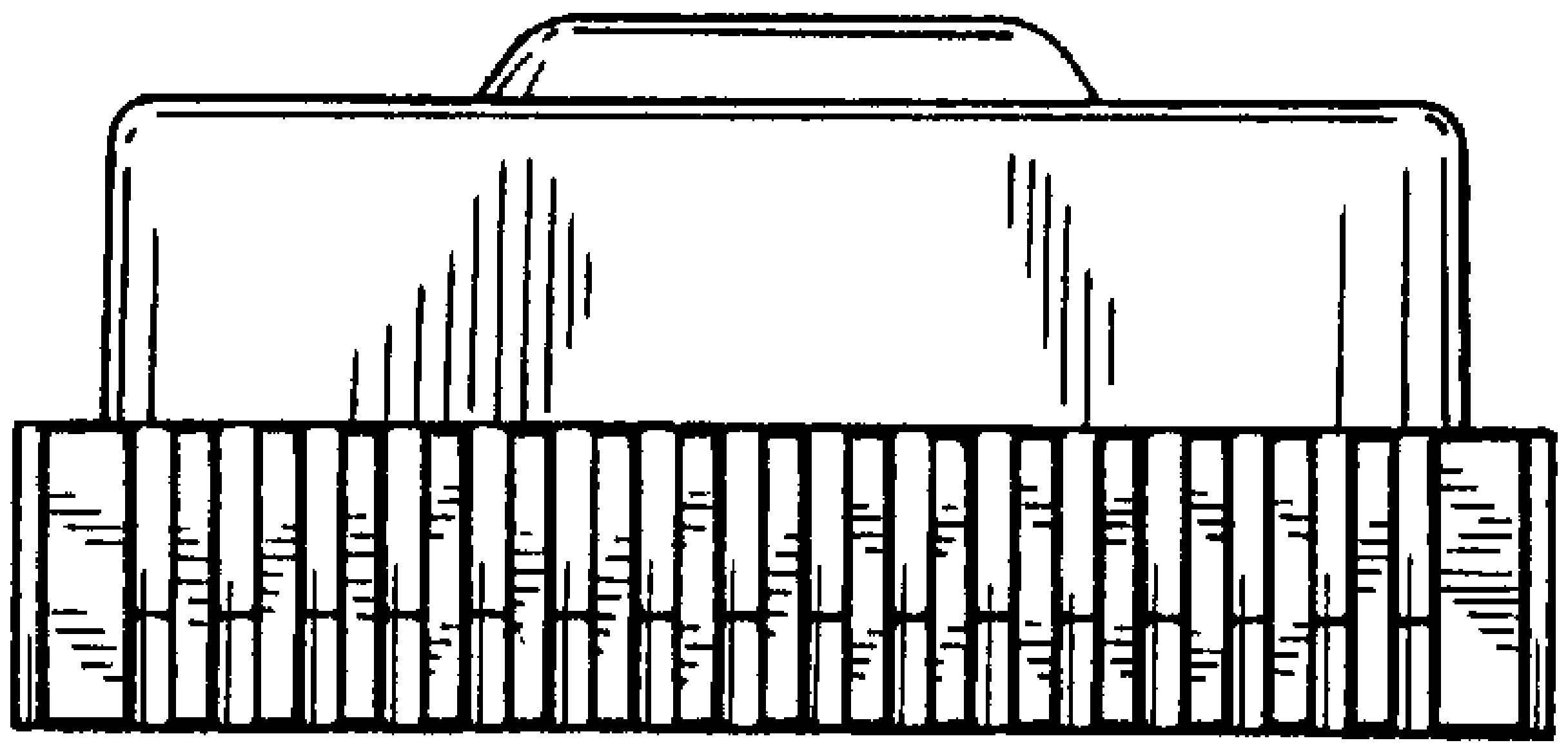

FIG. 18

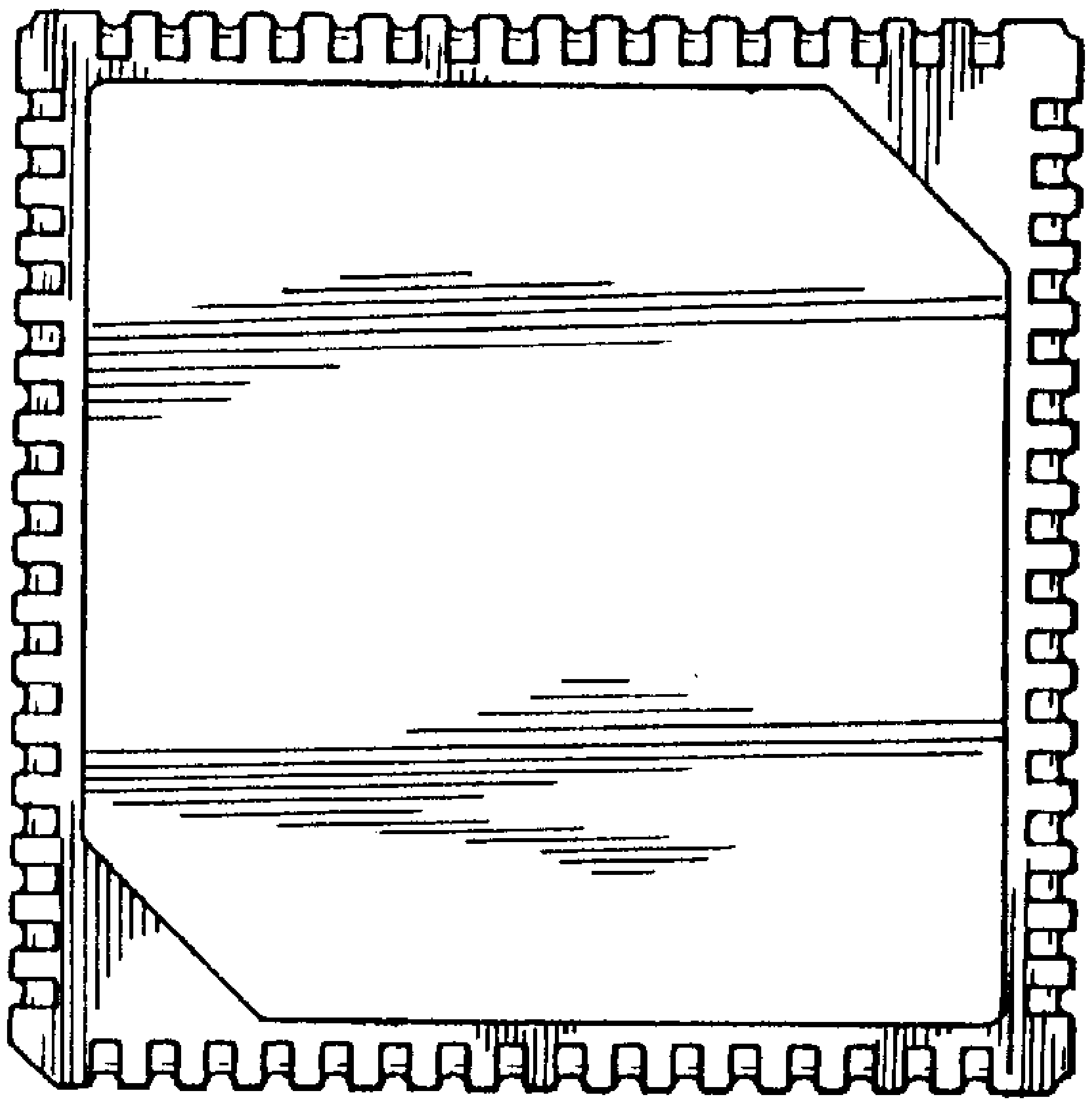

FIG. 17